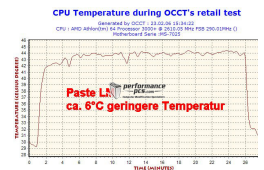
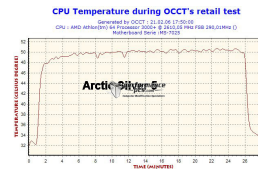
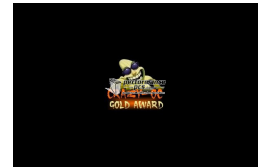




Phobya Liquid Metal Thermal Compound LM (0.5g)

\$4.95

Product Images





Short Description

LM liquid thermal compound is the latest generation of thermal interfaces. LM compound does not contain non-metallic additives such as silicones or metal oxides. This high purity allows greatly increased thermal transfer compared to standard compounds. LM liquid metal compound is made from 100% liquid metal and is produced in a highly advanced production and development process made for the highest requirements. Dwarfing all conventional thermal compounds and featuring easy application in combination with a thermal conductivity increased ten-fold over conventional compound, this is the ultimate thermal transfer solution.

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A multitude of tests and user reviews have shown that liquid metal thermal compounds leave all conventional thermal compounds (known to us) far behind in the dust.

Important: LM liquid metal thermal compound is not suitable for use on Aluminum surfaces.

Comparison (see image gallery): CPU temperatures can be lowered from approx. 50°C to 44°C - an improvement by 6°C!

Note: This Item can not be shipped using DHL

Specifications

Extent of delivery:

Syringe with dosing top for finest application and cap

Gross weight: approx. 3.2g

Sufficient for multiple applications

Please note the following points:

- LM liquid thermal compound is currently the best thermal interface for electronic components. It can be used on CPU, GPU and other components, providing an improved cooling performance by approx. 3°C to 7°C compared to conventional thermal compounds.
- LM compound was developed for high-end cooling applications and must only be applied to contact surfaces such as Copper, Nickel, Silver or Gold. It must not be applied to Aluminum surfaces!
- **IMPORTANT:** LM compound is electrically conductive, hence all contact with conductor paths must be avoided. Being applied to the cooling surface, this conductivity is no hazard, as both contact surface (e.g. heatspreader or DIE) and heatsink themselves are already electrically conductive.
- LM compound does not contain Mercury or other toxic heavy metals such as Lead. It is hence not toxic, not flammable, not explosive and does emit vapors. A safety data sheet may be requested via E-Mail.
- Despite being liquid, LM compound has a high contact tensions (by adhesive forces) and can not flow from the contact surface when applied properly. It is mandatory that only a very small amount (a small drop) is applied with e.g. a brush, barely covering the surface. If these instructions are being followed, the contact surface (e.g. the CPU) does not need to be sealed, as the LM compound can not flow from the surface even with vertical mounting.

Additional Information

Brand	Phobyra
SKU	PH-31001-D
Weight	0.2500
TIM Type	Phase Change Metal Alloy

